ON Semiconductor 10/15/2019				
Base Part		MM3Z7V5B	HF	Pb-free
Orderable Part		MM3Z7V5B	Total weight (mg)	4.58939
Homogenous Material	Weight (mg)	Substance in Mat.	CAS#	% Avg. Weight
Die		Silicon (Si)	7440-21-3	94.9
		Gold (Au)	7440-57-5	4.7
	0.03	Aluminum (AI)	7429-90-5	0.4
Lead Frame		Silver (Ag)	7440-22-4	0.39840637
		Chromium (Cr)	7440-47-3	0.19920319
		Manganese (Mn)	7439-96-5	0.79681275
		Nickel (Ni)	7440-02-0	40.83665339
	1.004	Iron (Fe)	7439-89-6	57.7689243
Mold Compound- Black		Ortho Cresol Novolac Resin	29690-82-2	10.82974154
		Carbon Black (C)	1333-86-4	0.54000157
		Fused Silica (SiO2)	60676-86-0	78.78022835
	3.44999	Phenolic Resin (Novolac)	9003-35-4	9.85002855
Plating	0.1	Tin (Sn)	7440-31-5	100
Wire Bond - Cu	0.0054	Copper (Cu)	7440-50-8	100

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the most accurate information, we cannot guarantee to its accuracy since the data has been compiled based on the ranges provided, and some information provided by the subcontractors and raw material suppliers may have been withheld to protect their business proprietary information. Thus this information is provided only as estimates, and do not include trace levels fo dopants and metal materials contained within silicon devices in the finished products. There is no intentional use of Mercury, Hexavalent Chromium, Cadmium, PBB or PBDE (5 of the 6 RoHS banned substances) in this or any of our other products. For further explanation on material composition calculations, please view our Product Chemical Content Brochure at:

http://www.onsemi.com/pub/Collateral/BRD8022-D.PDF